

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing Of Claims:

1.-10. (Canceled)

11. (New) A hot-film air mass meter for recording an air flow rate in one of an intake air tract and a charge air tract of an internal combustion engine, comprising:

a sensor chip; and

a substrate part that accommodates the sensor chip allocated to a channel that has flowing therethrough at least a partial mass flow of a flowing medium, the sensor chip extending into the channel, wherein:

the substrate part, into which the sensor chip is integrated downstream with respect to a flow direction and lying behind a leading edge, corresponds to one of a component that is able to be fastened separately to an electronics module and a unit extruded onto the electronics module.

12. (New) The hot-film air mass meter as recited in Claim 11, wherein the sensor chip is accommodated in a recess used to limit the sensor chip on all sides as a cavity at a circumflowed side of the substrate part.

13. (New) The hot-film air mass meter as recited in Claim 11, wherein an upper side of the sensor chip forms a flat running surface with a side of the substrate part.

14. (New) The hot-film air mass meter as recited in Claim 11, wherein a tight adhesion is formed between a hybrid chamber and the channel.

15. (New) The hot-film air mass meter as recited in Claim 12, wherein a floor of the recess used as the cavity in the substrate part is flat.

16. (New) The hot-film air mass meter as recited in Claim 11, wherein the electronics module lies on a support surface of a plug housing that has an opening pointing towards the channel.

17. (New) The hot-film air mass meter as recited in Claim 11, further comprising:
a printed circuit board accommodated in the electronics module and being developed in a U profile by one of being set with pins and adhered.
18. (New) The hot-film air mass meter as recited in Claim 11, wherein the sensor chip is fixed within the recess by latching projections.
19. (New) A method for producing a printed circuit board having a sensor chip for recording a flow of a flowing material in a channel, comprising:
stamping a sheet metal part to be used as an electronics module;
producing printed circuit traces on the printed circuit board;
mounting a plastic substrate tongue that accommodates the sensor chip on the printed circuit board; and
assembling the plastic substrate tongue with the sensor chip and assembling the printed circuit board with electronics components.
20. (New) A method for producing a printed circuit board having a sensor chip for recording a flow of a flowing material in a channel, comprising:
developing a printed circuit board in a heat sink technology, the printed circuit board having an integrated sheet metal profile;
layering the printed circuit board is layered onto a pressure compensating substrate;
pressing-fit the printed circuit board together with the pressure compensating substrate;
at least one of clamping, adhering, and welding a substrate part accommodating the sensor chip to the printed circuit board;
assembling the printed circuit board with electronics components; and
assembling the mounted substrate part with the sensor chip.